

**描述 / Descriptions**

SOD-323 塑封封装 肖特基二极管。  
Schottky Diode in a SOD-323 Plastic Package.

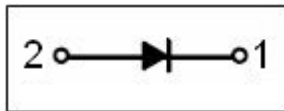
**特征 / Features**

低正向压降，低压整流，反极性保护，低功耗应用，无卤产品。  
low forward voltage drop , Low Voltage Rectification , Inverse Polarity Protection , Low Power Consumption Applications , HF Product.

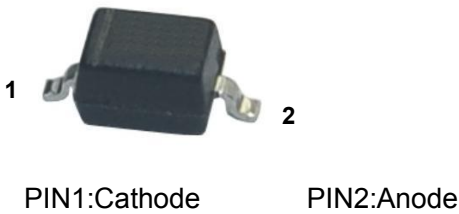
**用途 / Applications**

肖特基二极管。  
Schottky diode.

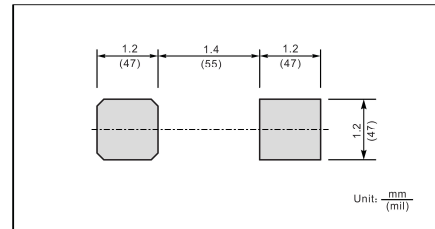
**内部等效电路 / Equivalent Circuit**



**引脚排列 / Pinning**



The recommended mounting pad size



**印章代码 / Marking**

Model	B1040WS
Marking	HSZ

**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$	40	V
RMS Reverse Voltage	$V_{R(RMS)}$	28	V
DC Reverse Voltage	$V_R$	40	V
Maximum Average Forward Current at Ta=25°C	$I_o$	1.0	A
Power dissipation	$P_d$	250	mW
Peak Forward Surge Current, 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	$I_{FSM}$	20	A
Typical Junction Capacitance at $V_R=10V$ , $f=1MHz$	$C_j$	20	pF
Storage and Operating Junction Temperature Range	$T_j, T_{stg}$	-55 ~ +125	°C

**电性能参数 / Electrical Characteristics(Ta=25°C)**

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Maximum Instantaneous Forward Voltage	$V_F$	$I_F=0.5A$	0.51	V
		$I_F=0.7A$	0.55	
Maximum DC Reverse Current at Rated DC Blocking Voltage	$I_R$	$V_R=20V$	50	uA

电参数曲线图 / Electrical Characteristic Curve

Fig.1 Power Derating Curve

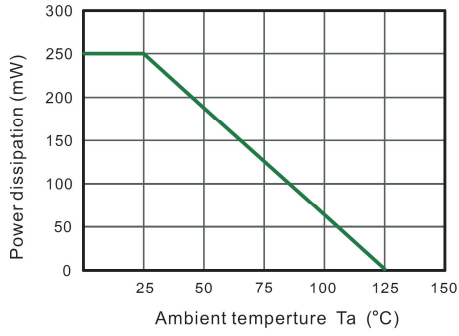


Fig.2 Typical Reverse Characteristics

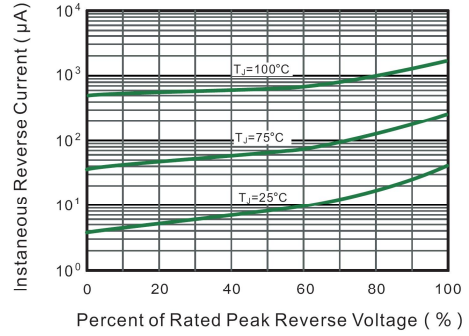


Fig.3 Typical Forward Characteristic

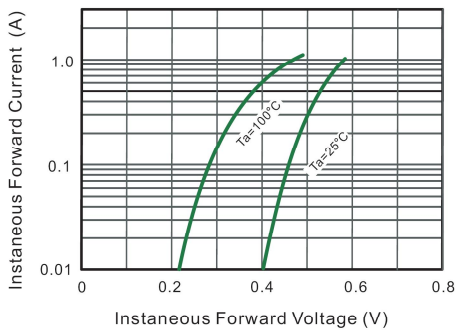


Fig.4 Typical Junction Capacitance

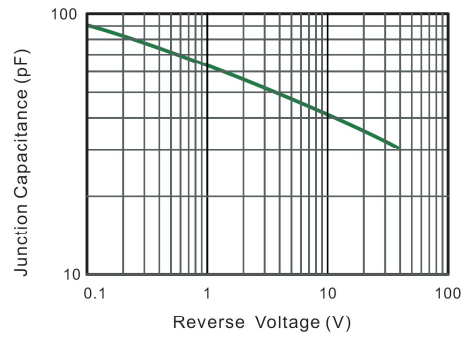
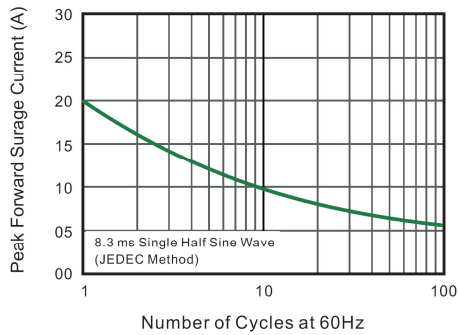
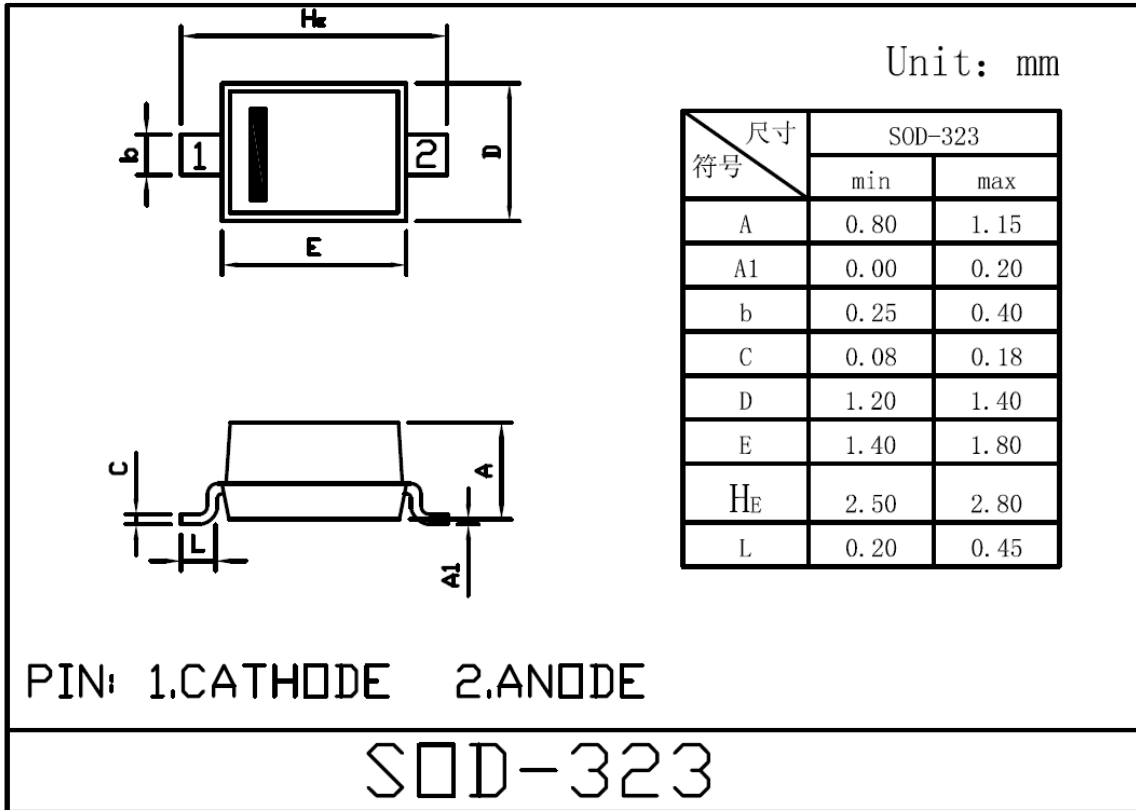


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



外形尺寸图 / Package Dimensions



印章说明 / Marking Instructions



说明：

H： 为公司代码

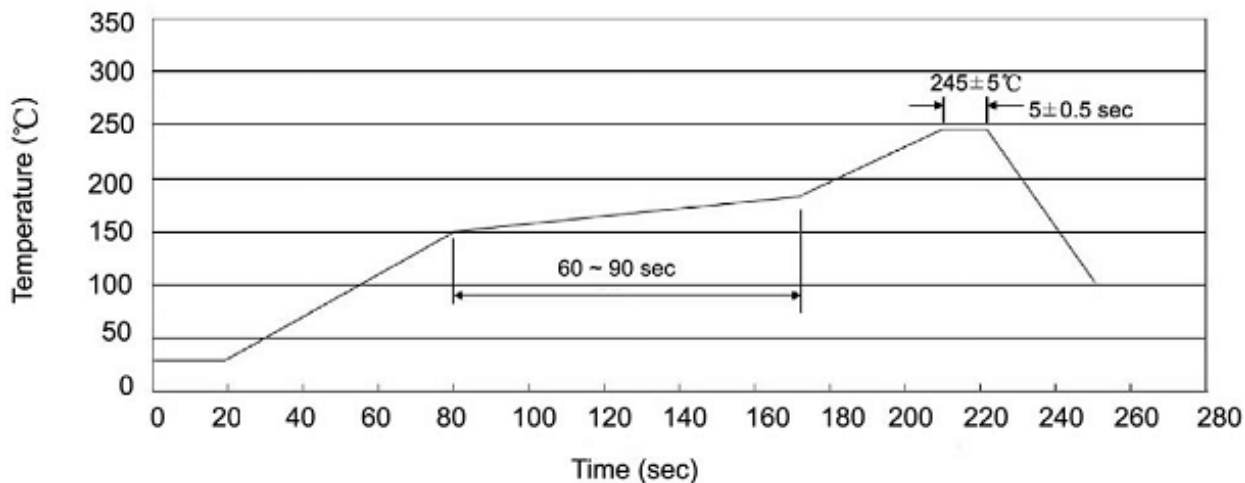
SZ： 为型号代码

Note:

H: Company Code.

SZ: Product Type.

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec；
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec；
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-323	3,000	10	30,000	6	180,000	7" x8	180×120×180	390×385×205

**使用说明 / Notices**